

IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors



NXPSC08650

Silicon Carbide Diode

4 May 2015

Product data sheet

1. General description

Silicon Carbide Schottky diode in a SOD59A (TO-220AC) plastic package, designed for high frequency switched-mode power supplies.

2. Features and benefits

- Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

3. Applications

- Power factor correction
- Telecom/Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED/OLED TV
- Motor Drives

4. Quick reference data

Table 1. Quick reference data

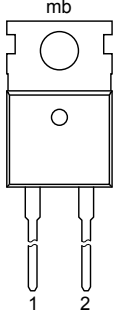
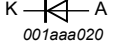
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	-	650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_{mb} \leq 120\text{ °C}$; square-wave pulse; Fig. 1 ; Fig. 2	-	-	8	A
T_j	junction temperature		-	-	175	°C
Static characteristics						
V_F	forward voltage	$I_F = 8\text{ A}$; $T_j = 25\text{ °C}$; Fig. 4	-	1.5	1.7	V



Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Dynamic characteristics						
Q_r	recovered charge	$I_F = 8\text{ A}$; $V_R = 400\text{ V}$; $dI_F/dt = 500\text{ A}/\mu\text{s}$; $T_J = 25\text{ }^\circ\text{C}$; Fig. 5	-	13	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-220AC (SOD59A)</p>	
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
NXPSC08650	TO-220AC	Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC	SOD59A

7. Marking

Table 4. Marking codes

Type number	Marking code
NXPSC08650	NXPSC08650

8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{RRM}	repetitive peak reverse voltage		-	650	V
V _{RWM}	crest working reverse voltage		-	650	V
V _R	reverse voltage	DC	-	650	V
I _{F(AV)}	average forward current	δ = 0.5; T _{mb} ≤ 120 °C; square-wave pulse; Fig. 1; Fig. 2	-	8	A
I _{FRM}	repetitive peak forward current	δ = 0.5; t _p = 25 μs; T _{mb} ≤ 120 °C; square-wave pulse	-	16	A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse	-	48	A
		t _p = 10 μs; T _{j(init)} = 25 °C; square-wave pulse	-	385	A
T _{stg}	storage temperature		-55	175	°C
T _j	junction temperature		-	175	°C

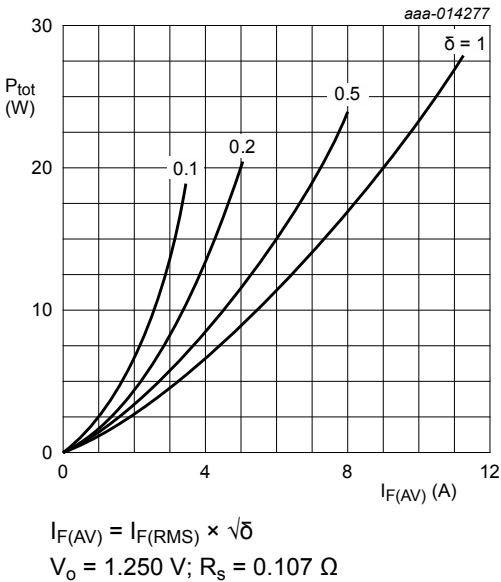


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

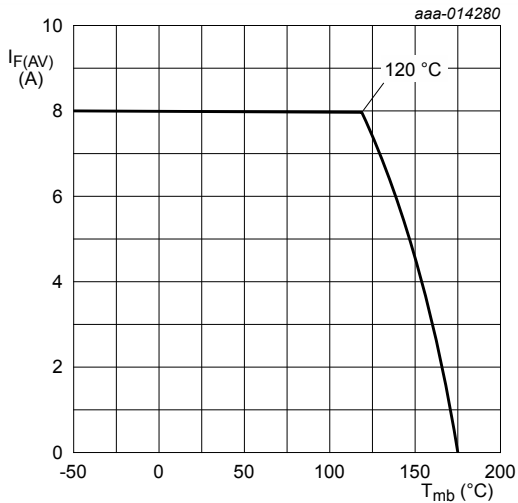


Fig. 2. Forward current as a function of mounting base temperature; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 3		-	-	2.3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	60	-	K/W

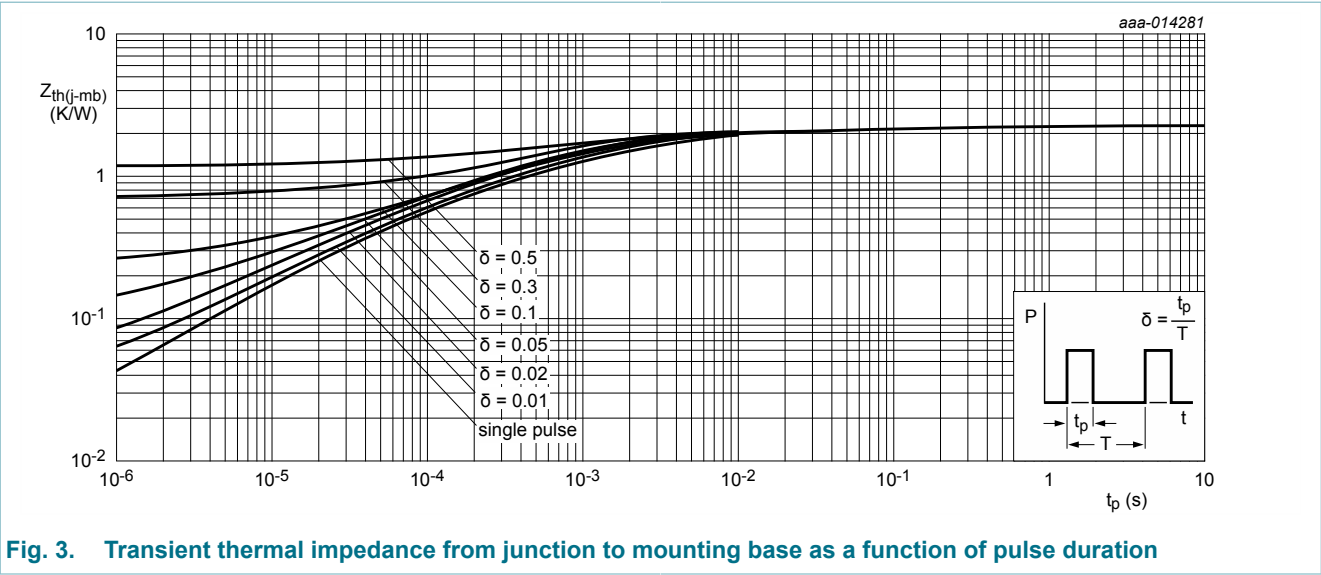
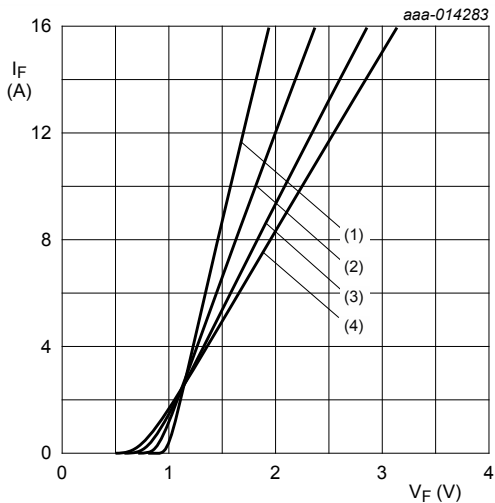


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 8 A; T _j = 25 °C; Fig. 4		-	1.5	1.7	V
		I _F = 8 A; T _j = 150 °C; Fig. 4		-	1.8	2.1	V
I _R	reverse current	V _R = 650 V; T _j = 25 °C		-	-	230	μA
		V _R = 650 V; T _j = 150 °C		-	-	700	μA
Dynamic characteristics							
Q _r	recovered charge	I _F = 8 A; dI _F /dt = 500 A/μs; V _R = 400 V; T _j = 25 °C; Fig. 5		-	13	-	nC
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; T _j = 25 °C		-	260	-	pF
		f = 1 MHz; V _R = 300 V; T _j = 25 °C		-	30	-	pF
		f = 1 MHz; V _R = 600 V; T _j = 25 °C		-	24	-	pF



V₀ = 1.250 V; R_s = 0.107 Ω
(1) T_j = 25 °C; typical values
(2) T_j = 100 °C; typical values
(3) T_j = 150 °C; typical values
(4) T_j = 175 °C; typical values

Fig. 4. Forward current as a function of forward voltage; typical values

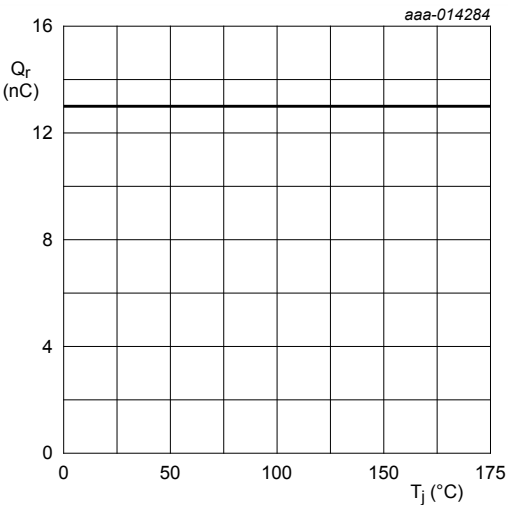


Fig. 5. Forward current as a function of forward voltage; typical values

11. Package outline

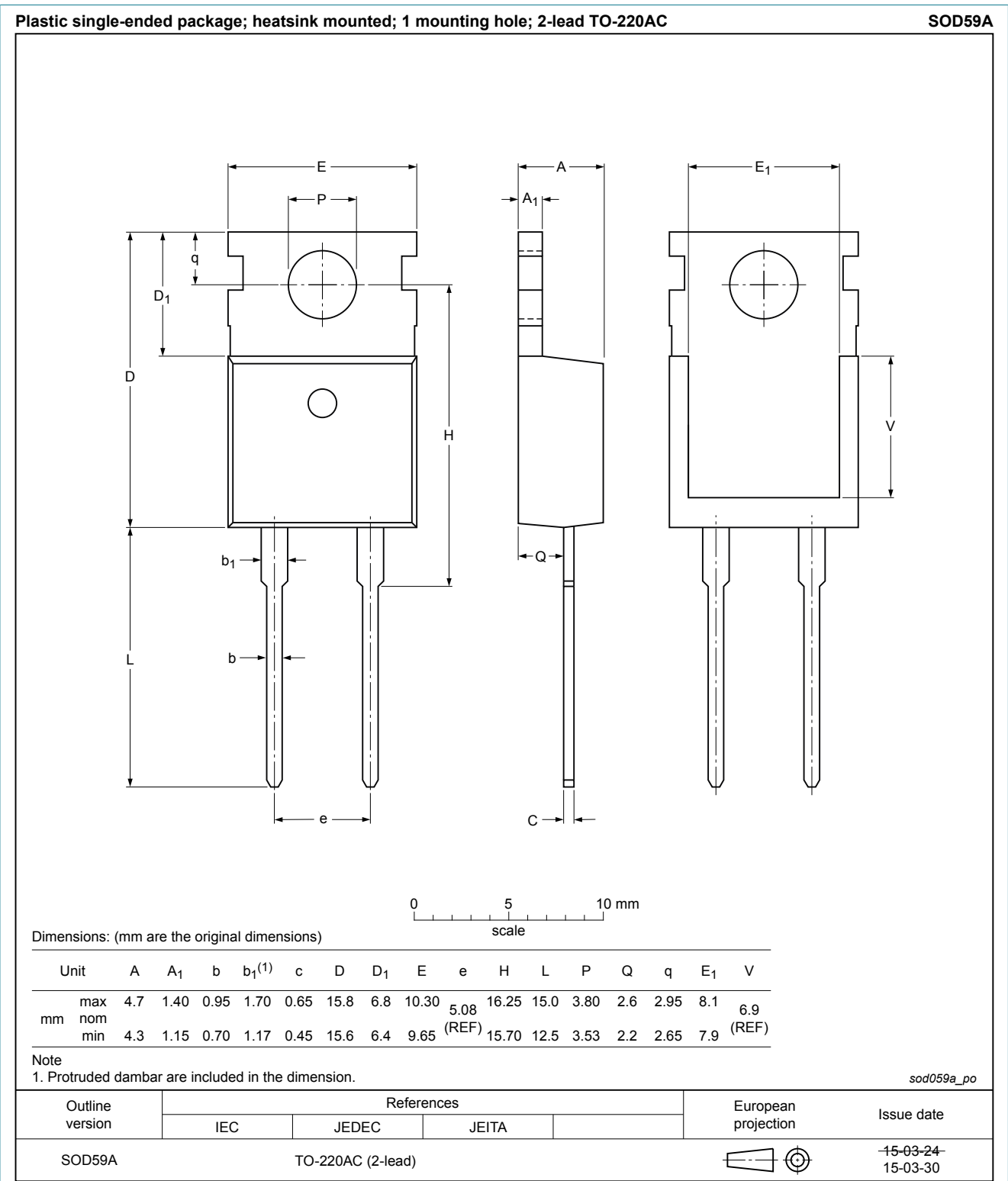


Fig. 6. Package outline TO-220AC (SOD59A)

12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

1	General description	1
2	Features and benefits	1
3	Applications	1
4	Quick reference data	1
5	Pinning information	2
6	Ordering information	2
7	Marking	2
8	Limiting values	3
9	Thermal characteristics	4
10	Characteristics	5
11	Package outline	6
12	Legal information	7
12.1	Data sheet status	7
12.2	Definitions	7
12.3	Disclaimers	7
12.4	Trademarks	8

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